News Releases 2019 (From January to December 2019)

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December 26, 2019	Tradeshow Notice: 21th IC & Sensor Packaging Technology EXPO
September 9, 2019	Tradeshow Notice: SEMICON taiwan 2019
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	Product maintenance information: Discontinued and Replacement Parts (SC18-0135)
April 10, 2019	Notification Regarding Discontinuation of Maintenance Support (Affected equipment: BESTEM-D01,D02 series)
March 18, 2019	Tradeshow Notice: SEMICON China 2019
January 11, 2019	Tradeshow Notice: 20th IC & Sensor Packaging Technology EXPO